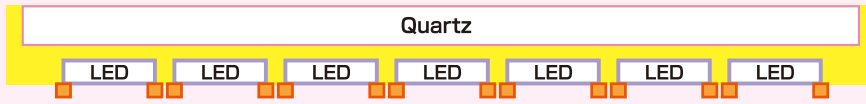


# ウエハーレベルパッケージ

## Wafer Level Packaging

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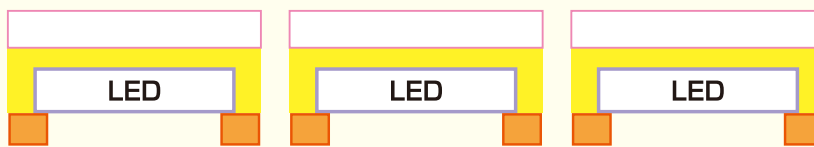
### 電極形成 (Cuメッキ) Formation of Copper Electrode



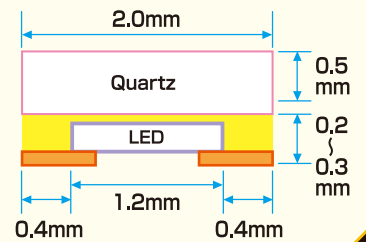
- SIPR-7126 厚膜メッキレジスト
- Thick Film Plating Resist

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### ダイシングによる個片化 Singularization by Dicing



- 2020PKG断面
- 2020PKG Cross Section



### メッキ部詳細 Details of Device Structure

Chip: Bridgelux BXCD45

